



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUC100N08S5N043	Issued	17. February 2022
MA#	MA005699182		
Package	PG-TDSON-8-34	Weight*	112.98 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.432	1.27	1.27	12679	12679
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	iron	7439-89-6	0.053	0.05		468	
	non noble metal	copper	7440-50-8	52.842	46.78	46.84	467721	468330
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	372	372
encapsulation	organic material	carbon black	1333-86-4	0.075	0.07		660	
	plastics	epoxy resin	-	5.894	5.22		52166	
	inorganic material	silicondioxide	60676-86-0	31.333	27.73	33.02	277340	330166
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13930	13930
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1852	1852
solder	non noble metal	tin	7440-31-5	0.034	0.03		303	
	noble metal	silver	7440-22-4	0.043	0.04		378	
	non noble metal	lead	7439-92-1	1.632	1.44	1.51	14449	15130
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	16.828	14.89	14.90	148947	149141
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5656	5656
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2740	2744
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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